

IXYS

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Thyristor / Diode Modules


One of the essential advantages of power semiconductor modules compared to discrete designs is the electrical isolation between the baseplate of the module and the parts subject to voltage (3.6 kV_{RMS} tested). This makes possible the mount-down of any number of the same or different modules on a common heatsink. It is feasible to use standard housings with appropriate accessories for designing compact power converter operating from AC mains up to 690 V.

Plastic Housing with DCB Substrate

IXYS has succeeded in simplifying the conventional multilayer module construction by the DCB (Direct Copper Bonding) technique.

Other features are:

- top-side electrical terminals with captured nuts;
- series-connected diode/diode, thyristor/diode and thyristor/thyristor modules;
- easy assembly.

All thyristor modules with DCB ceramic base contacts are available in volume with two standardized twin plugs (2.8 mm x 0.8 mm) for gate and auxiliary cathode control terminals (version 1). Modules in TO-240 housing of the version 8 are delivered with gate plugs only (without auxiliary cathode terminal; mounting screws available on request). The module housing is designed for adequate clearance and creepage distance resulting in  recognition by Underwriters Laboratories, Inc., USA for all types.

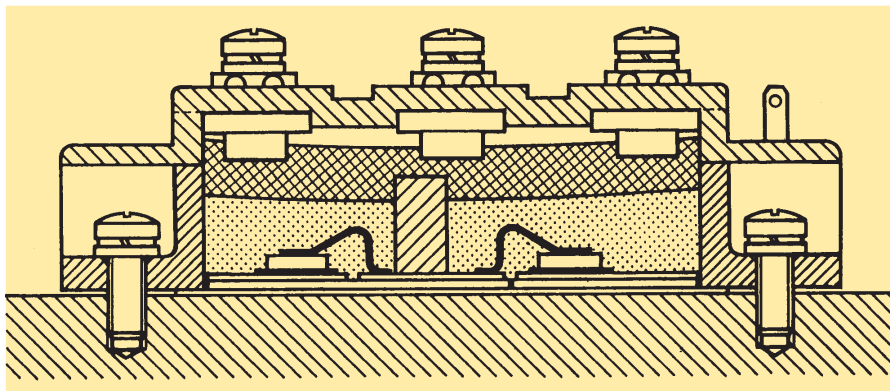


Fig. 2: Principal cross section of an IXYS module with DCB technology

New Generation Silicon Chips

The figures 1 a-c show cross sections of the used thyristor and diode chips in the passivation area. All chips are designed by applying separation diffusion processes such that the zones responsible for the surface field strength are located at the upper chip side. This results in the capability of soldering the entire chip area onto the DCB ceramic substrate without a molybdenum strain buffer, which in turn leads to good stability of the chips as well as to large area heat dissipation if a load is applied. All zones at the edges which are decisive for the blocking stability are coated with passivation glasses the coefficient of expansion of which match that of silicon. Silicon chips increasingly use planar technology with guard rings and channel stoppers to reduce electrical surface fields. This chip design supercedes the design of thyristor chips which were fabricated with passivation moats so that modules of the new series designed with the updated state-of-the-art utilize planar passivated chips processed by separation diffusion techniques. The contact areas of the chips possess physical vapor deposited metal layers. For the user the improved properties are:

- Excellent long-term stability of blocking currents and blocking voltages,
- increased life time of the internal soldered connections,
- high power cycling capability ($\geq 50\,000$).

The thyristor/diode chips have been optimized with regard to their turn-off

parameters: decreasing the carrier lifetime results in reduced stored charges Q_s , which in turn significantly reduces requirements for RC-snubbers for over-voltage protection. Cost reduction and improved efficiency are the benefits of these characteristics. By re-developing the silicon chips, improvements of the firing characteristics were achieved by specifying a higher "gate current not to fire" I_{GD} resulting in substantially less susceptibility to misfiring. This leads to greater safety of operation and higher reliability of the equipment.

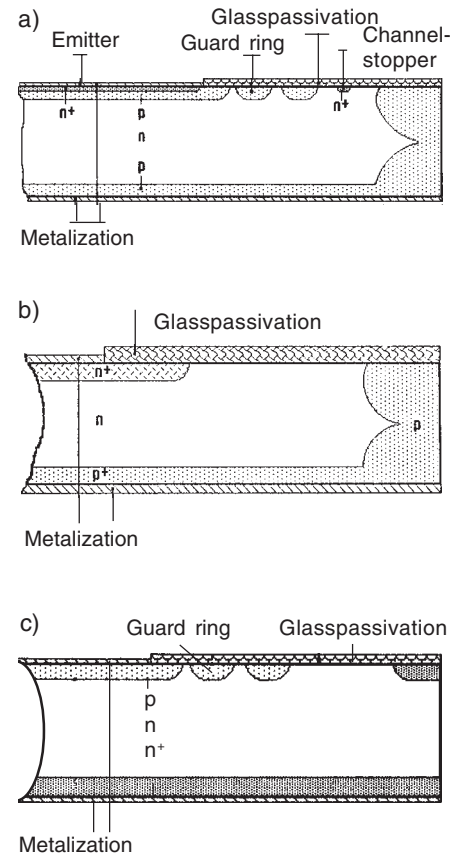


Fig. 1a-c: Cross sections of thyristor and diode chips in the passivation area

- a) glassivated planar thyristor chip with separation diffusion, type CWP
- b) glassivated planar diode chip with separation diffusion, type DWN
- c) glassivated planar diode chip, type DWP (reverse polarity of DWN chips)

Thyristors, SCRs

(SCR = Silicon Controlled Rectifier)

Phase Control Thyristors

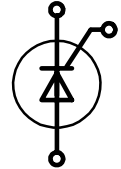
Thyristors are very rugged devices. Compared to all other controlled semi-conductor components, they feature the highest current capacity per chip area, especially at high voltage. They are mainly used as control devices in 50 and 60 Hz AC mains equipment.

Principal applications are static converter circuits for speed control of DC-drives, or switching and control functions for temperature, lighting, soft-start, etc. in single-phase and three-phase AC switch configurations. Phase control thyristors are

designed for optimal forward conduction and reverse blocking characteristics, due to only moderate requirements for turn-on and turn-off parameters.

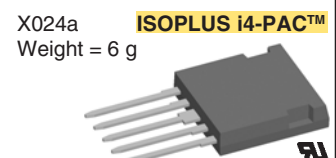
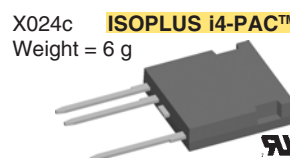
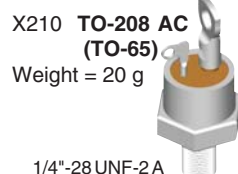
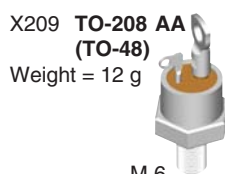
Phase Control Thyristors

$I_{TAV} = 16 - 60 \text{ A}$

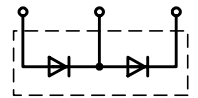


Type	V_{RRM} V_{DRM}	I_{TAV} $T_C = 85^\circ\text{C}$	I_{TRMS}	I_{TSM} 45°C 10 ms A	$\left[\frac{dv}{dt}\right]_c$	V_{TO}	r_T	T_{VJM}	R_{thJC}	R_{thCH}	Fig. No.	Package style	
► New	V	A	A	A	V/μs	V	mΩ	°C	K/W	K/W		Outline drawings on page 188 - 224	
CS 8-08 io2 CS 8-12 io2	800 1200	16	25	250	1000	1.0	18	125	1.5	1.0	X208	X005a Weight = 2 g	TO-220AB
CS 19-08 ho1 CS 19-12 ho1	800 1200	19	29	160	500	0.85	27.0	125	1.0	0.25	X005a		
CS 19-08 ho1S CS 19-12 ho1S	800 1200	19	29	160	500	0.85	27.0	125	1.0	0.25	X011b	X007a Weight = 2	TO-220ABFP
CS 19-08 ho1C CS 19-12 ho1C	800 1200	13	35	100	500	0.87	29	125	1.7	0.6	X010a		
CS 20-12 io1 CS 20-14 io1 CS 20-16 io1	1200 1400 1600	19	30	200	1000	1.1	40	125	0.62	0.2	X014a	X010a Weight = 2 g	ISOPLUS220™
CS 20-22 moF1	2200	18		200	2500			125	0.92	0.15	X024c		
CS 22-08 io1M CS 22-12 io1M	800 1200	22	30	300	500	0.9	18	150	2.5	0.5	X007A		
CS 23-08 io2 CS 23-12 io2 CS 23-16 io2	800 1200 1600	25	50	450	1000	1.0	10	125	1.0	0.6	X209	X011b Weight = 2 g	TO-263AB
CS 29-08 io1C CS 29-12 io1C	800 1200	23 $T_C = 95^\circ\text{C}$	35	200	1000	0.82	16.5	150	1.2	0.6	X010a		
CS 30-12 io1 CS 30-14 io1 CS 30-16 io1	1200 1400 1600	31	49	300	1000	0.9	15	125	0.62	0.2	X014a	X014a Weight = 6 g	TO-247 AD
CS 35-08 io4 CS 35-12 io4 CS 35-14 io4	800 1200 1400	63	120	1200	1000	0.85	3.5	125	0.4	0.2	X210		
CS 45-08 io1 CS 45-12 io1 CS 45-16 io1	800 1200 1600	48 $T_C = 75^\circ\text{C}$	75	520	1000	0.85	11	140	0.62	0.2	X014a	X016a Weight = 5 g	ISOPLUS247™
CS 45-16 io1R ①	1600										X016a		
► CLA 50E1200HB ► CLA 50E1200TC	1200	50 $T_C = 125^\circ\text{C}$	75	550	1000	0.92	7.8	150	0.4	0.25	X014a X019		
CS 60-12 io1 CS 60-14 io1 CS 60-16 io1	1200 1400 1600	48 $T_C = 105^\circ\text{C}$	75	1500	1000	0.85	3.7	140	0.32	0.15	X015	X019 Weight = 5 g	TO-268 AA
FCC 21-12 io	1200	21 $T_C = 90^\circ\text{C}$	-	300	1000	-	-	125	1.00	0.32	X024a		

① isolated 2500 V_{RMS}

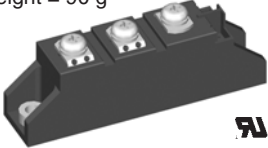
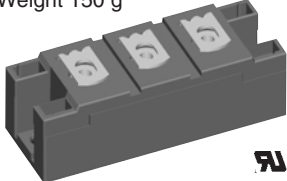


Diode Modules, Single and Dual

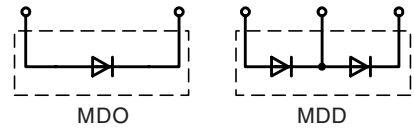


MDD

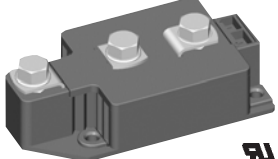
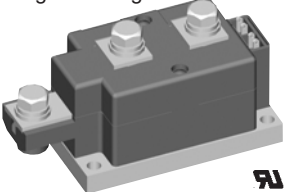
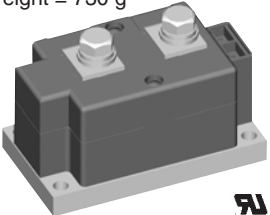
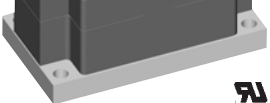
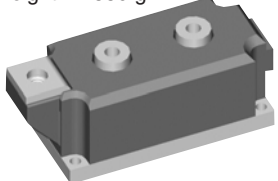
$$I_{FAV} = 36-224 \text{ A}$$

Type	V _{RRM}	I _{FAV} @ T _C		I _{FRMS}	I _{FSM} 45°C 10 ms	V _{TO}	r _T	T _{VJM}	R _{thJC} per Chip	R _{thCH} per Chip	Fig. No.	Package style		
►New	V	A	°C	A	A	V	mΩ	°C	K/W	K/W		Outline drawings on page 188 - 224		
MDD 26-08N1B MDD 26-12N1B MDD 26-14N1B MDD 26-16N1B MDD 26-18N1B	800 1200 1400 1600 1800	36	100	60	650	0.8	6.1	150	1.0	0.2	X125e	TO-240 AA Weight = 90 g 		
MDD 44-08N1B MDD 44-12N1B MDD 44-14N1B MDD 44-16N1B MDD 44-18N1B	800 1200 1400 1600 1800	59	100	100	1150	0.8	4.3	150	0.59	0.2				
MDD 56-08N1B MDD 56-12N1B MDD 56-14N1B MDD 56-16N1B MDD 56-18N1B	800 1200 1400 1600 1800	71	100	150	1400	0.8	3.0	150	0.51	0.2				
MDD 72-08N1B MDD 72-12N1B MDD 72-14N1B MDD 72-16N1B MDD 72-18N1B	800 1200 1400 1600 1800	99	100	180	1700	0.8	2.3	150	0.35	0.2				
MDD 95-08N1B MDD 95-12N1B MDD 95-14N1B MDD 95-16N1B MDD 95-18N1B MDD 95-20N1B MDD 95-22N1B	800 1200 1400 1600 1800 2000 2200	120	105	180	2800	0.75	1.95	150	0.26	0.2				
MDD 142-08N1 MDD 142-12N1 MDD 142-14N1 MDD 142-16N1 MDD 142-18N1	800 1200 1400 1600 1800	165	100	300	4700	0.8	1.3	150	0.21	0.1			X126c	X126c Weight 150 g 
MDD 172-08N1 MDD 172-12N1 MDD 172-14N1 MDD 172-16N1 MDD 172-18N1	800 1200 1400 1600 1800	190	100	300	6600	0.8	0.8	150	0.21	0.1				
MDD 200-14N1 MDD 200-16N1 MDD 200-18N1 MDD 200-22N1	1400 1600 1800 2200	224	100	350	10500	0.8	1.5	150	0.13	0.1				

Diode Modules, Single and Dual

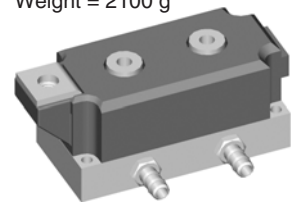


$I_{FAV} = 270-950 \text{ A}$

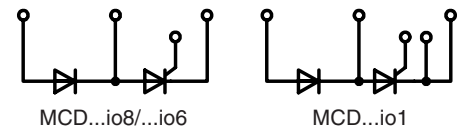
Type	V_{RRM}	I_{FAV}	T_C	I_{FRMS}	I_{FSM} 45°C 10 ms	V_{TO}	r_T	T_{VJM}	R_{thJC} per Chip	R_{thCH} per Chip	Fig. No.	Package style
►New	V	A	°C	A	A	V	mΩ	°C	K/W	K/W		Outline drawings on page 188 - 224
MDD 220-08N1 MDD 220-12N1 MDD 220-14N1 MDD 220-16N1 MDD 220-18N1	800 1200 1400 1600 1800	270	100	450	8500	0.75	0.9	150	0.129	0.04	X129c	X129c Weight = 310 g 
MDD 250-08N1 MDD 250-12N1 MDD 250-14N1 MDD 250-16N1	800 1200 1400 1600	290	100	450	11000	0.75	0.75	150	0.129	0.04		
MDD 255-12N1 MDD 255-14N1 MDD 255-16N1 MDD 255-18N1 MDD 255-20N1 MDD 255-22N1	1200 1400 1600 1800 2000 2200	270	100	450	9500	0.8	0.6	150	0.140	0.04	X131c	X131c Weight = 750 g
MDD 310-08N1 MDD 310-12N1 MDD 310-14N1 MDD 310-16N1 MDD 310-18N1 MDD 310-20N1 MDD 310-22N1	800 1200 1400 1600 1800 2000 2200	305	100	480	11500	0.75	0.63	150	0.129	0.04	X129c	
MDD 312-12N1 MDD 312-14N1 MDD 312-16N1 MDD 312-18N1 MDD 312-20N1 MDD 312-22N1	1200 1400 1600 1800 2000 2200	310	100	520	10500	0.8	0.6	150	0.120	0.04	X131c	X132b Weight = 730 g
MDD 600-12N1* MDD 600-16N1 MDD 600-18N1 MDD 600-22N1	1200 1600 1800 2200	600	111	1818	24000 150°C	0.75	0.2	150	0.062	0.02	X136a	
MDO 500-12N1 MDO 500-14N1 MDO 500-16N1 MDO 500-18N1 MDO 500-20N1 MDO 500-22N1	1200 1400 1600 1800 2000 2200	560	85	880	15000	0.8	0.38	140	0.072	0.024	X132b	
► MDD 950-12N1W* ► MDD 950-16N1W ► MDD 950-18N1W ► MDD 950-22N1W	1200 1600 1800 2200	950	$T_w = 45^\circ\text{C}$	1773	2400 150°C	0.75	0.2	150	$R_{thJW} = 0.09$	-	X136b	X136a Weight = 1550 g 

* for other configurations please contact factory

X136b
Weight = 2100 g



Thyristor / Diode Modules

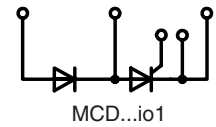


$I_{TAV} = 27-165 \text{ A}$

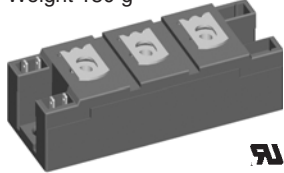
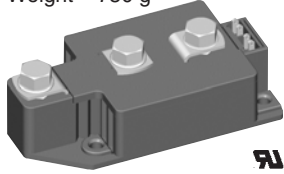
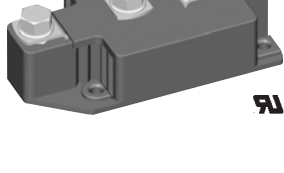
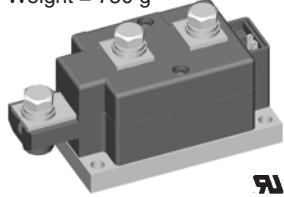
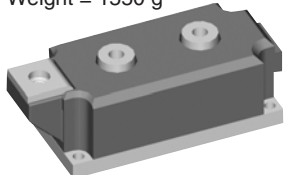
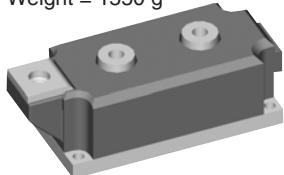
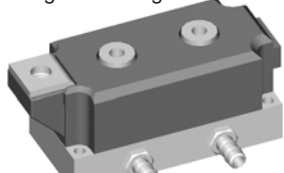
Type	V_{RRM} V_{DRM}	I_{TAV} @ T_C	I_{TRMS}	I_{TSM} 45°C 10ms	V_{TO}	r_T	T_{VJM}	R_{thJC} per Chip	R_{thCH} per Chip	Fig. No.	Package style
► New	V	A °C	A	A	V	mΩ	°C	K/W	K/W		Outline drawings on page 188 - 224
MCD 26-08io1B MCD 26-12io1B MCD 26-14io1B MCD 26-16io1B	800 1200 1400 1600	27 85	50	520	0.85	11	125	0.88	0.2	X125b	X027a SOT-227B Weight = 30 g miniBLOC
MCD 26-08io8B MCD 26-12io8B MCD 26-14io8B MCD 26-16io8B	800 1200 1400 1600	27 85	50	520	0.85	11	125	0.88	0.2	X125d	
MCD 40-12io6 MCD 40-16io6	1200 1600	38 85	60	500	0.85	9.5	125	0.6	0.1	X027a	
MCD 44-08io1B MCD 44-12io1B MCD 44-14io1B MCD 44-16io1B MCD 44-18io1B	800 1200 1400 1200 1600	49 85	80	1150	0.85	5.3	125	0.53	0.2	X125b	X125b TO-240 AA Weight = 90 g
MCD 44-08io8B MCD 44-12io8B MCD 44-14io8B MCD 44-16io8B MCD 44-18io8B	800 1200 1400 1600 1800	49 85	80	1150	0.85	5.3	125	0.53	0.2	X125d	
MCD 56-08io1B MCD 56-12io1B MCD 56-14io1B MCD 56-16io1B MCD 56-18io1B	800 1200 1400 1600 1800	60 85	100	1500	0.85	3.7	125	0.45	0.2	X125b	
MCD 56-08io8B MCD 56-12io8B MCD 56-14io8B MCD 56-16io8B MCD 56-18io8B	800 1200 1400 1600 1800	60 85	100	1500	0.85	3.7	125	0.45	0.2	X125d	X125d TO-240 AA Weight = 90 g
MCD 72-08io1B MCD 72-12io1B MCD 72-14io1B MCD 72-16io1B MCD 72-18io1B	800 1200 1400 1600 1800	85 85	180	1700	0.85	3.2	125	0.3	0.2	X125b	
MCD 72-08io8B MCD 72-12io8B MCD 72-14io8B MCD 72-16io8B MCD 72-18io8B	800 1200 1400 1600 1800	85 85	180	1700	0.85	3.2	125	0.3	0.2	X125d	
MCD 94-20io1B MCD 94-22io1B	2000 2200	104 85	180	1700	0.85	3.2	125	0.22	0.2	X125b	X126b Weight 150 g
MCD 95-08io1B MCD 95-12io1B MCD 95-14io1B MCD 95-16io1B MCD 95-18io1B	800 1200 1400 1600 1800	116 85	180	2250	0.8	2.4	125	0.22	0.2	X125d	
MCD 95-08io8B MCD 95-12io8B MCD 95-14io8B MCD 95-16io8B MCD 95-18io8B	800 1200 1400 1600 1800	116 85	180	2250	0.8	2.4	125	0.22	0.2	X125d	
MCD 132-08io1 MCD 132-12io1 MCD 132-14io1 MCD 132-16io1 MCD 132-18io1	800 1200 1400 1600 1800	130 85	300	4750	0.8	1.5	125	0.23	0.1	X126b	
MCD 161-20io1 MCD 161-22io1	2000 2200	165 85	300	6000	0.8	1.6	125	0.155	0.07		

Data according to IEC 60747 and refer to a single diode or thyristor unless otherwise stated.

Thyristor / Diode Modules

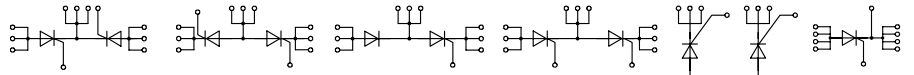


$I_{TAV} = 181 - 700 \text{ A}$

Type	V_{RRM} V_{DRM}	I_{TAV} @ T_C	I_{TRMS}	I_{TSM} 45°C 10 ms	V_{T0}	r_T	T_{VJM}	R_{thJC} per Chip	R_{thCH} per Chip	Fig. No.	Package style
► New	V	A	°C	A	V	mΩ	°C	K/W	K/W		Outline drawings on page 188 - 224
MCD 162-08io1 MCD 162-12io1 MCD 162-14io1 MCD 162-16io1 MCD 162-18io1	800 1200 1400 1600 1800	181 85	300	6000	0.88	1.15	125	0.155	0.07	X126b	X126b Weight 150 g 
MCD 200-14io1 MCD 200-16io1 MCD 200-18io1	1400 1600 1800	216 85	340	8000	0.8	1.0	125	0.13	0.05		
MCD 224-20io1 MCD 224-22io1	2000 2200	240 85	400	8000	0.8	0.76	130	0.139	0.04	X131b	
MCD 220-08io1 MCD 220-12io1 MCD 220-14io1 MCD 220-16io1	800 1200 1400 1600	250 85	400	8500	0.9	1.0	140	0.139	0.04	X129b	X129b Weight = 750 g 
MCD 225-12io1 MCD 225-14io1 MCD 225-16io1 MCD 225-18io1	1200 1400 1600 1800	221 85	400	8000	0.8	0.76	130	0.157	0.04	X131b	
MCD 250-08io1 MCD 250-12io1 MCD 250-14io1 MCD 250-16io1 MCD 250-18io1	800 1200 1400 1600 1800	287 85	450	9000	0.85	0.82	140	0.129	0.04	X129b	X131b Weight = 750 g 
MCD 255-12io1 MCD 255-14io1 MCD 255-16io1 MCD 255-18io1	1200 1400 1600 1800	250 85	450	9000	0.8	0.68	130	0.14	0.04	X131b	
MCD 310-08io1 MCD 310-12io1 MCD 310-14io1 MCD 310-16io1 MCD 310-18io1	800 1200 1400 1600 1800	320 85	500	9200	0.8	0.82	140	0.112	0.04	X129b	X136a Weight = 1550 g 
MCD 310-20io1 MCD 310-22io1	2000 2200	320 85	500	8000	0.8	0.82	140	0.112	0.04	X129b	
MCD 312-12io1 MCD 312-14io1 MCD 312-16io1 MCD 312-18io1	1200 1400 1600 1800	320 85	520	9200	0.8	0.68	140	0.12	0.04	X131b	
MCD 500-12io1* MCD 500-16io1 MCD 500-18io1	1200 1600 1800	500 89	1294	18200 125°C	0.85	0.27	125	0.062	0.02	X136a	X136b Weight = 2100 g 
MCD 500-22io1	2200	500 80	1071	15400 125°C	0.88	0.46	125	0.062	0.02	X136b	
MCD 700-12io1W* MCD 700-16io1W MCD 700-18io1W	1200 1600 1800	700 $T_W = 42^\circ\text{C}$	1331	18200 125°C	0.85	0.27	125	0.062	$R_{thJW} = 0.09$	X136b	

* for other configurations please contact factory

Thyristor Modules



VCK

VCA

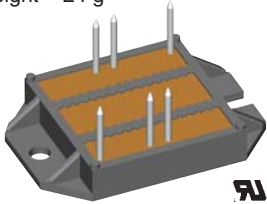
VCD

VCC

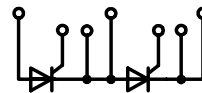
VCC
2x105

VCO

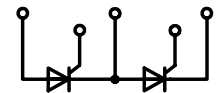
$I_{TAV} = 105 - 180 \text{ A}$

Type	V_{RRM} V_{DRM}	I_{TAV} @ T_C	I_{TRMS}	I_{TSM} 45°C 10 ms	V_{TO}	r_T	T_{VJM}	R_{thJC} per Chip	R_{thCH} per Chip	Fig. No.	Package style
► New	V	A °C	A	A	V	mΩ	°C	K/W	K/W		Outline drawings on page 188 - 224
VCK 105-08io7 VCK 105-12io7 VCK 105-14io7 VCK 105-16io7 VCK 105-18io7	800 1200 1400 1600 1800	105 85	180	2250	0.8	2.4	125	0.26	0.2	X102	<p>X102 Weight = 24 g</p>  <p>See data sheet for pin arrangement</p>
VCA 105-08io7 VCA 105-12io7 VCA 105-14io7 VCA 105-16io7 VCA 105-18io7	800 1200 1400 1600 1800	105 85	180	2250	0.8	2.4	125	0.26	0.2		
VCD 105-08io7 VCD 105-12io7 VCD 105-14io7 VCD 105-16io7 VCD 105-18io7	800 1200 1400 1600 1800	105 85	180	2250	0.8	2.4	125	0.26	0.2		
VCC 105-08io7 VCC 105-12io7 VCC 105-14io7 VCC 105-16io7 VCC 105-18io7	800 1200 1400 1600 1800	105 85	180	2250	0.8	2.4	125	0.26	0.2		
VCC 2x105-08io7 VCC 2x105-12io7 VCC 2x105-14io7 VCC 2x105-16io7 VCC 2x105-18io7	800 1200 1400 1600 1800	105 85	180	2250	0.8	2.4	125	0.26	0.2		
VCO 132-08io7 VCO 132-12io7 VCO 132-14io7 VCO 132-16io7 VCO 132-18io7	800 1200 1400 1600 1800	130 85	200	3600	0.8	1.65	150	0.25	0.1		
VCO 180-08io7 VCO 180-12io7 VCO 180-14io7 VCO 180-16io7 VCO 180-18io7	800 1200 1400 1600 1800	180 90	280	4500	0.75	1.23	150	0.17	0.06		

Thyristor Modules

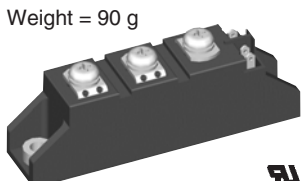
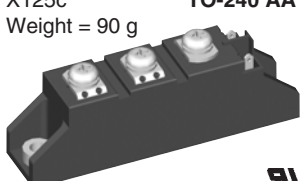



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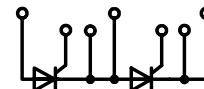


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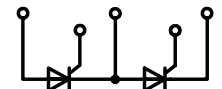
$I_{TAV} = 18-116 \text{ A}$

Type	V_{RRM} V_{DRM} V	I_{TAV} A	@ T_C °C	I_{TRMS} A	I_{TSM} 45°C 10 ms A	V_{TO} V	r_T mΩ	T_{VJM} °C	R_{thJC} per Chip K/W	R_{thCH} per Chip K/W	Fig. No.	Package style Outline drawings on page 188 - 224
MCC 19-08io1B MCC 19-12io1B MCC 19-14io1B MCC 19-16io1B	800 1200 1400 1600	18	85	40	400	0.85	18	125	1.3	0.2	X125a	 <p>X125a Weight = 90 g</p> <p>TO-240 AA</p>  <p>X125c Weight = 90 g</p> <p>TO-240 AA</p>  <p>X125a</p>
MCC 19-08io8B MCC 19-12io8B MCC 19-14io8B MCC 19-16io8B	800 1200 1400 1600	18	85	40	400	0.85	18	125	1.3	0.2	X125c	
MCC 21-08io8B MCC 21-12io8B MCC 21-14io8B MCC 21-16io8B	800 1200 1400 1600	21	85	33	320	0.85	15	125	1.1	0.2	X125c	
MCC 26-08io1B MCC 26-12io1B MCC 26-14io1B MCC 26-16io1B	800 1200 1400 1600	27	85	50	520	0.85	11	125	0.88	0.2	X125a	
MCC 26-08io8B MCC 26-12io8B MCC 26-14io8B MCC 26-16io8B	800 1200 1400 1600	27	85	50	520	0.85	11	125	0.88	0.2	X125c	
MCC 44-08io1B MCC 44-12io1B MCC 44-14io1B MCC 44-16io1B MCC 44-18io1B	800 1200 1400 1600 1800	49	85	80	1150	0.85	5.3	125	0.53	0.2	X125a	
MCC 44-08io8B MCC 44-12io8B MCC 44-14io8B MCC 44-16io8B MCC 44-18io8B	800 1200 1400 1600 1800	49	85	80	1150	0.85	5.3	125	0.53	0.2	X125c	
MCC 56-08io1B MCC 56-12io1B MCC 56-14io1B MCC 56-16io1B MCC 56-18io1B	800 1200 1400 1600 1800	60	85	100	1500	0.85	3.7	125	0.45	0.2	X125a	
MCC 56-08io8B MCC 56-12io8B MCC 56-14io8B MCC 56-16io8B MCC 56-18io8B	800 1200 1400 1600 1800	60	85	100	1500	0.85	3.7	125	0.45	0.2	X125c	
MCC 72-08io1B MCC 72-12io1B MCC 72-14io1B MCC 72-16io1B MCC 72-18io1B	800 1200 1400 1600 1800	85	85	180	1700	0.85	3.2	125	0.3	0.2	X125a	
MCC 72-08io8B MCC 72-12io8B MCC 72-14io8B MCC 72-16io8B MCC 72-18io8B	800 1200 1400 1600 1800	85	85	180	1700	0.85	3.2	125	0.3	0.2	X125c	
MCC 94-20io1B MCC 94-22io1B	2000 2200	104	85	180	1700	0.85	3.2	125	0.22	0.2	X125a	
MCC 95-08io1B MCC 95-12io1B MCC 95-14io1B MCC 95-16io1B MCC 95-18io1B	800 1200 1400 1600 1800	116	85	180	2250	0.8	2.4	125	0.22	0.2	X125a	

Thyristor Modules, Dual

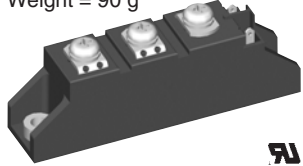
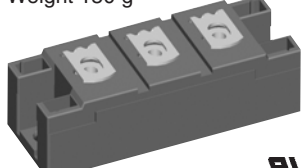
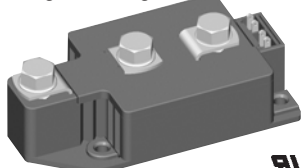
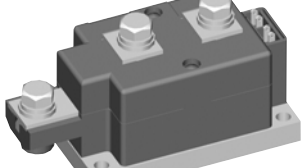
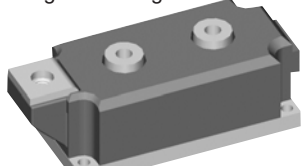
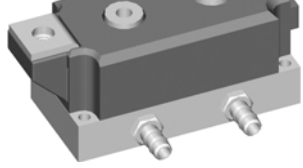



MCC...io1B



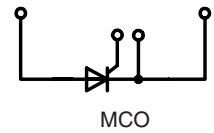
MCC...io8B

$I_{TAV} = 116-700 \text{ A}$


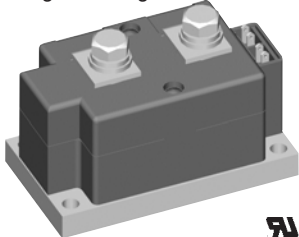
Type	V_{RRM} V_{DRM}	I_{TAV} @ T_C	I_{TRMS}	I_{TSM} 45°C 10 ms	V_{TO}	r_T	T_{VJM}	R_{thJC} per Chip	R_{thCH} per Chip	Fig. No.	Package style
► New	V	A °C	A	A	V	mΩ	°C	K/W	K/W		Outline drawings on page 188 - 224
MCC 95-08io8B MCC 95-12io8B MCC 95-14io8B MCC 95-16io8B MCC 95-18io8B	800 1200 1400 1600 1800	116 85	180	2250	0.8	2.4	125	0.22	0.2	X125c	X125c Weight = 90 g 
MCC 132-08io1 MCC 132-12io1 MCC 132-14io1 MCC 132-16io1 MCC 132-18io1	800 1200 1400 1600 1800	130 85	300	4750	0.8	1.5	125	0.23	0.1	X126a	X126a Weight 150 g 
MCC 161-20io1 MCC 161-22io1	2000 2200	165 85	300	6000	0.8	1.6	125	0.155	0.07		
MCC 162-08io1 MCC 162-12io1 MCC 162-14io1 MCC 162-16io1 MCC 162-18io1	800 1200 1400 1600 1800	181 85	300	6000	0.88	1.15	125	0.155	0.07		
MCC 170-12io1 MCC 170-14io1 MCC 170-16io1 MCC 170-18io1	1200 1400 1600 1800	203 85	350	5400	0.8	1.0	130	0.164	0.04	X131a	X131a Weight = 750 g 
MCC 200-14io1 MCC 200-16io1 MCC 200-18io1	1400 1600 1800	216 85	340	8000	0.8	1.0	125	0.13	0.05	X126a	X126a Weight = 750 g 
MCC 220-08io1 MCC 220-12io1 MCC 220-14io1 MCC 220-16io1 MCC 220-18io1	800 1200 1400 1600 1800	250 85	400	8500	0.9	1.0	140	0.139	0.04	X129a	X129a Weight = 750 g 
MCC 224-20io1 MCC 224-22io1	2000 2200	240 85	400	8000	0.8	0.76	130	0.139	0.04	X131a	X131a Weight = 750 g 
MCC 225-12io1 MCC 225-14io1 MCC 225-16io1 MCC 225-18io1	1200 1400 1600 1800	221 85	400	8000	0.8	0.76	130	0.157	0.04		
MCC 250-08io1 MCC 250-12io1 MCC 250-14io1 MCC 250-16io1 MCC 250-18io1	800 1200 1400 1600 1800	287 85	450	9000	0.85	0.82	140	0.129	0.04	X129a	X129a Weight = 1550 g 
MCC 255-12io1 MCC 255-14io1 MCC 255-16io1 MCC 255-18io1	1200 1400 1600 1800	250 85	450	9000	0.8	0.68	130	0.14	0.04	X131a	X131a Weight = 2100 g
MCC 310-08io1 MCC 310-12io1 MCC 310-14io1 MCC 310-16io1 MCC 310-18io1	800 1200 1400 1600 1800	320 85	500	9200	0.8	0.82	140	0.112	0.04	X129a	X129a Weight = 1550 g
MCC 312-12io1 MCC 312-14io1 MCC 312-16io1 MCC 312-18io1	1200 1400 1600 1800	320 85	520	9200	0.8	0.68	140	0.12	0.04	X131a	X131a Weight = 2100 g
MCC 500-12io1* MCC 500-14io1 MCC 500-16io1 MCC 500-18io1	1200 1400 1600 1800	500 89	785	18200 125°C	0.85	0.27	125	0.062	0.02	X136a	X136a Weight = 2100 g
MCC 500-22io1*	2200	500 80	1071	15400 125°C	0.88	0.46	125	0.062	0.02		
MCC 700-12io1W MCC 700-16io1W MCC 700-18io1W	1200 1600 1800	700 $T_w = 42^\circ\text{C}$	1331	18200 125°C	0.85	0.27	125	0.062	$R_{thJW} = 0.09$	X136b	X136b Weight = 2100 g

* for other configurations please contact factory

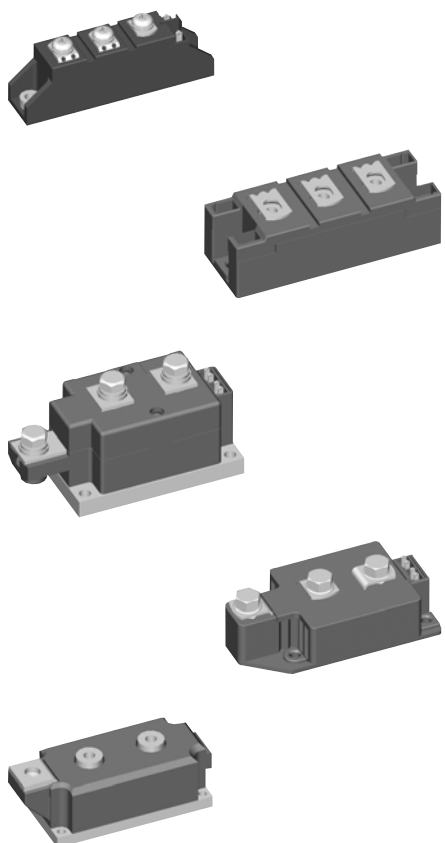
Thyristor Modules, Single



$I_{TAV} = 31-600 \text{ A}$

Type	V_{RRM} V_{DRM}	I_{TAV}	T_C	I_{TRMS}	I_{TSM} 45°C 10 ms	V_{TO}	r_T	T_{VJM}	R_{thJC} per Chip	R_{thCH} per Chip	Fig. No.	Package style
► New	V	A	°C	A	A	V	mΩ	°C	K/W	K/W		Outline drawings on page 188 - 224
MCO 25-12io6 MCO 25-16io6	1200 1600	31	80	49	370	0.85	14	150	1.1	0.5	X027a	SOT-227B miniBLOC Weight = 30 g 
MCO 50-12io6 MCO 50-16io6	1200 1600	54	80	85	740	0.9	5.8	150	0.72	0.4		
► MCO 75-12io6 ► MCO 75-16io6	1200 1600	77	80	121	1070	0.85	5.5	150	0.45	0.2		
MCO 100-12io6 MCO 100-16io6	1200 1600	99	80	156	1400	0.85	4.5	150	0.35	0.15		
MCO 150-12io1 MCO 150-16io1	1200 1600	149	80	234	2000	0.8	3.8	150	0.2	0.1		
MCO 450-20io1 MCO 450-22io1	2000 2200	464	85	750	15000	0.77	0.42	130	0.072	0.024	X132a	Weight = 730 g 
MCO 500-12io1 MCO 500-14io1 MCO 500-16io1 MCO 500-18io1	1200 1400 1600 1800	560	85	880	17000	0.8	0.38	140	0.072	0.024		
MCO 600-16io1 MCO 600-18io1 MCO 600-20io1 MCO 600-22io1	1600 1800 2000 2200	600	85	928	15000	0.77	0.42	140	0.065	0.02		

Optional Accessories for Thyristor / Diode Modules

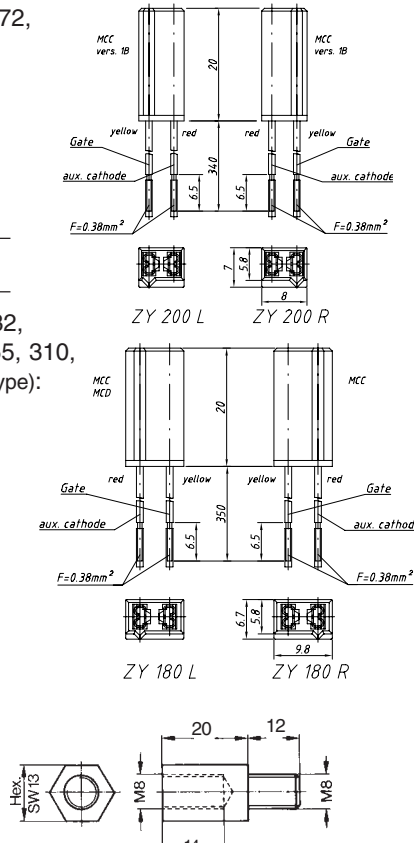


For module-types MCC 19, 26, 44, 56, 60, 72, 94 and 95 version 1:
Keyed Gate Cathode twin plugs with wire length = 350 mm;
gate = yellow, cathode = red
Type **ZY 200 L** (L = Left for pin pair 4/5)
Type **ZY 200 R** (R = Right for pin pair 6/7)

For ZY 180 and ZY 200: UL Styles 1385

For module types MCC/MCD/MCO 122, 132, 161, 162, 170, 200, 220, 224, 225, 250, 255, 310, 312, 500 and MII 400 (for MCD/MCO only L-type):
Keyed Gate Cathode twin plugs with wire length = 350 mm
gate = yellow, cathode = red
Type **ZY 180 L** (L = Left for pin pair 4/5)
Type **ZY 180 R** (R = Right for pin pair 6/7)

For module types MCC/MCD/MDD 220, 250, 310
Threaded spacer for higher Anode / Cathode construction:
Type **ZY 250** (material brass)



Design Information

For Thyristors, Diodes, Thyristor / Diode Modules and Rectifier Bridges

Surge current	The 60 Hz value of I_{TSM} is 10 % higher than the 50 Hz value The I_{TSM} value at T_{VJM} is 10 to 15 % lower than the 45°C value
Limiting I^2t	50 Hz: I^2t (in A ² s) = $I_{TSM} (A) \cdot I_{TSM} (A) \cdot 0.005 (s)$; use rated I_{TSM} value (10 ms) 60 Hz: I^2t (in A ² s) = $I_{TSM} (A) \cdot I_{TSM} (A) \cdot 0.0042 (s)$; use 60-Hz-value of I_{TSM}
Forward current	The average current ratings in tables are mostly specified for temperature conditions of: $T_A = 45^\circ C$, $T_C = 85^\circ C$ or $T_C = 100^\circ C$. For other temperature conditions, the current ratings can be calculated using the following formulas, applicable up to 400 Hz.
$I_{TAV} = \frac{-V_{TO} + \sqrt{V_{TO}^2 + 4 \cdot k^2 \cdot r_T \cdot P}}{2 \cdot k^2 \cdot r_T} \quad \text{where} \quad P = \frac{T_{VJM} - T_C}{R_{thJC}} \quad \text{or} \quad P = \frac{T_{VJM} - T_A}{R_{thJA}}$	
I_{TAV} (A), P (W); V_{TO} (V); r_T (Ω), T_{VJM} ($^\circ C$), T_C ($^\circ C$), T_A ($^\circ C$) R_{thJC} (K/W), R_{thJA} (K/W)	
$k^2 = 1$ for DC current $k^2 = 2.5$ for sinusoidal half wave current $k^2 = 3.0$ for 120° rectangular current $k^2 = 6.0$ for 60° rectangular current	
The average forward current is limited by the RMS current value I_{TRMS} . When the calculated value I_{TAV} is higher than I_{TRMS}/k , replace it by $I_{TAV} = I_{TRMS}/k$.	